

===== WPI =====

TI -> Washing machine for cleaning circuit board after soldering - uses nozzle on each washing stage to discharge water when circuit board feed to stage is detected NoAbstract

AB - J05146766
- (Dwg.1/5)

PN - JP5146766 A 19930615 DW199328 B08B3/02 008pp

PR - JP19910316205 19911129

PA - (SHAF) SHARP KK

MC - V04-R03C X24-A09 X25-H09

DC - P43 V04 X24 X25

IC - B08B3/02 ;H05K3/26

AN - 1993-223692 [28]

===== PAJ =====

TI - CLEANER

AB - PURPOSE: To reduce the amt. of water to be used in the cleaner by controlling the water supplying time of a cleaning nozzle when the arrival of a material to be cleaned at the conveyor corresponding to each treating tank is detected.

- CONSTITUTION: A substrate 29 is conveyed by a net conveyor 1, when an operating switch is turned on, and a control relay X14 is energized. The substrate 29 is detected by a first photosensor 24 at the inlet to an ultrasonic cleaning tank 2, an inverter 30 is actuated, hence the first control relay X1 is energized, a contact X1A is closed, a ninth control relay X9 is energized, and an ultrasonic vibrator 47 is operated. When the arrival of the substrate at a rough washing tank 3 is detected by a photosensor 25, an inverter 31 is actuated, a water feed solenoid valve 12 is opened through the control relays X2 and X10, and water is sprinkled from a shower nozzle 9. The water is supplied for the time determined by the capacitor C1 and resistance R11. Washing tanks 4 and 5 are also operated in the same way.

PN - JP5146766 A 19930615

PD - 1993-06-15

ABD - 19930927

ABV - 017533

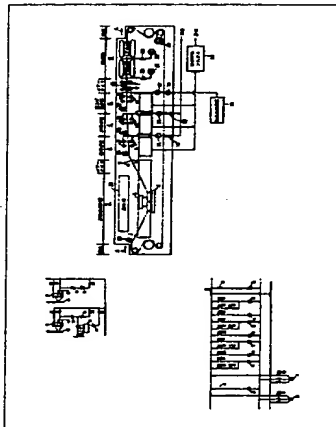
AP - JP19910316205 19911129

GR - C1114

PA - SHARP CORP

IN - SEGAWA HIROAKI

I - B08B3/02 ;H05K3/26



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